## Notice of References Cited

Application/Control No. 10/732,798	Applicant(s)/Patent Under Reexamination MIKAMI ET AL.		
Examiner	Art Unit		
Christian Wilson	2891	Page 1 of 1	

## **U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-5,677,545	10-1997	Shi et al.	257/40
	В	US-6,323,131	11-2001	Obeng et al.	438/687
	С	US-6,905,958	06-2005	Gracias et al.	438/643
	D	US-2004/0245518	12-2004	Ramanath et al.	257/009
	E	US-2005/0093162	05-2005	Gracias, David H.	257/759
	F	US-			
	G	US-			
	Н	US-		·	,
	1	US-			-
	J	US-			
	К	US-			
	L	US-			
	М	US-			

## FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0					
	Р	,				
	Ö					
	R					
	S					
	T					

## **NON-PATENT DOCUMENTS**

*.		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Ramanath et al., Self-assembled subnanolayers as interfacial adhesion enhancers and diffusion barriers for integrated circuits, Appl. Phys. Lett., 83 (July 2003) 383.
	V	Semaltianos et al., Copper chemical vapour deposition on organosilane-treated SiO <sub>2</sub> surfaces, Appl. Surf. Sci., <b>222</b> (2004) 102.
	w	Doppelt et al., High affinity self-assembled monolayers for copper CVD, Microelectronic Engineering, 76 (2004) 113.
	×	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)

Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.